捷多邦,专业PCB打样工厂**SN54H0148**5SN74HC148 8-LINE TO 3-LINE PRIORITY ENCODERS

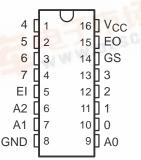
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 16 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Encode Eight Data Lines to 3-Line Binary (Octal)
- Applications Include:
 - n-Bit Encoding
 - Code Converters and Generators

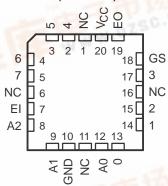
description/ordering information

The 'HC148 devices feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. These devices encode eight data lines to 3-line (4-2-1) binary (octal). Cascading circuitry (enable input El and enable output EO) has been provided to allow octal expansion without the need for external circuitry. Data inputs and outputs are active at the low logic level.

SN54HC148...J OR W PACKAGE SN74HC148...D, DW, N, OR NS PACKAGE (TOP VIEW)



SN54HC148 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	get	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
100	PDIP – N	Tube of 25	SN74HC148N	SN74HC148N	
	750.0	Tube of 40	SN74HC148D		
-40°C to 85°C	SOIC - D	Reel of 2500	SN74HC148DR	HC148	
		Reel of 250	SN74HC148DT		
Section 1	SOIC - DW	Reel of 2000	SN74HC148DWR	HC148	
	SOP - NS	Reel of 2000	SN74HC148NSR	HC148	
	CDIP – J	Tube of 25	SNJ54HC148J	SNJ54HC148J	
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC148W	SNJ54HC148W	
	LCCC – FK	Tube of 55	SNJ54HC148FK	SNJ54HC148FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

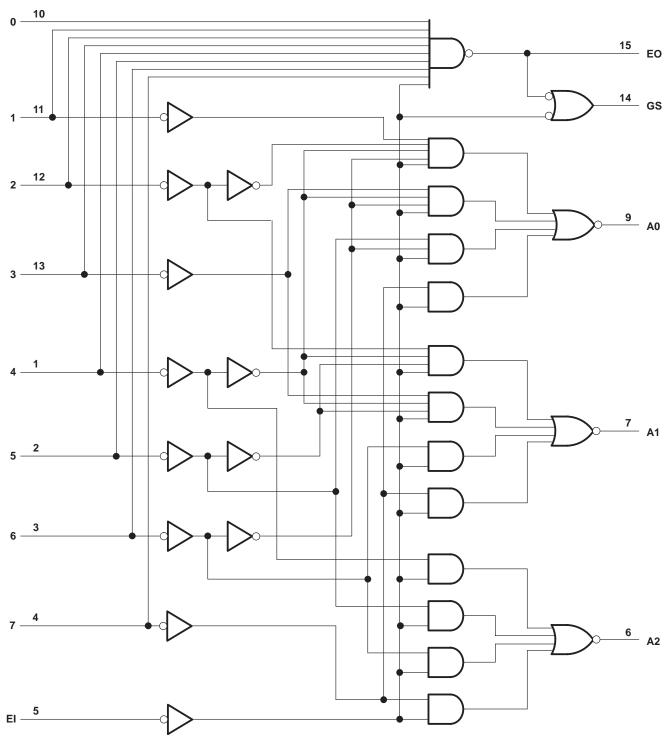


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FUNCTION TABLE

	INPUTS									C	UTPUT	S	
El	0	1	2	3	4	5	6	7	A2	A 1	Α0	GS	EO
Н	Х	Х	Χ	Χ	Χ	Χ	Χ	Х	Н	Н	Н	Н	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
L	Х	X	Χ	Χ	Χ	Χ	Χ	L	L	L	L	L	Н
L	Х	Χ	Χ	Χ	Χ	Χ	L	Н	L	L	Н	L	Н
L	Х	Χ	Χ	Χ	Χ	L	Н	Н	L	Н	L	L	Н
L	Х	Χ	Χ	Χ	L	Н	Н	Н	L	Н	Н	L	Н
L	Х	Χ	Χ	L	Н	Н	Н	Н	Н	L	L	L	Н
L	Х	Χ	L	Н	Н	Н	Н	Н	Н	L	Н	L	Н
L	Х	L	Н	Н	Н	Н	Н	Н	Н	Н	L	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	Н

logic diagram (positive logic)



Pin numbers shown are for the D, DW, J, N, NS, and W packages.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see		
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	C) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ _{JA} (see Note 2)	: D package	73°C/W
	DW package	57°C/W
	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T _{sto}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SI	SN54HC148		SN	174HC14	8	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
\vee_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		VCC = 6 V			1.8			1.8	
٧I	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature	•	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPITIONS		VCC	Т	A = 25°C	;	SN54H	IC148	SN74H	C148			
PARAMETER	IESI CC	TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			2 V	1.9	1.998		1.9		1.9				
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4				
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V		
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84				
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34				
	VI = VIH or VIL		2 V		0.002	0.1		0.1		0.1			
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1			
VOL			6 V		0.001	0.1		0.1		0.1	V		
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33			
					$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA		
lcc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ		
Ci			2 V to 6 V		3	10		10		10	pF		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	V	T,	T _A = 25°C		SN54F	IC148	SN74H	C148	LINUT		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			2 V		69	180		270		225			
	1–7	A0, A1, or A2	4.5 V		23	36		54		45			
			6 V		21	31		46		38			
			2 V		60	150		225		190			
		EO	4.5 V		20	30		45		38			
	0–7		6 V		17	26		38		33			
	0-7		2 V		75	190		285		240			
		GS	GS	GS	4.5 V		25	38		57		48	
			6 V		21	32		48		41			
^t pd	EI		2 V		78	195		295		245	ns		
		A0, A1, or A2	4.5 V		26	39		59		49			
			6 V		22	33		50		42			
			2 V		57	145		220		180			
		GS	4.5 V		19	29		44		36			
			6 V		16	25		38		31			
			2 V		66	165		250		205			
		EO	4.5 V		22	33		50		41			
			6 V		19	28		43		35			
			2 V		28	75		110		95			
t _t		Any	4.5 V		8	15		22		19	ns		
			6 V		6	13		19		16			

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operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	35	pF

PARAMETER MEASUREMENT INFORMATION From Output Test Input 50% 50% **Under Test Point** $C_L = 50 pF$ - tPLH → (see Note A) - tPHL ۷он In-Phase 90% Output **LOAD CIRCUIT ◆** t_{PHL} **VCC** 90% 90% Input 50% 90% Out-of-Phase 50% Output 10% VOL **VOLTAGE WAVEFORM VOLTAGE WAVEFORMS INPUT RISE AND FALL TIMES** PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f = 6$ ns, $t_f = 6$ ns.
 - C. The outputs are measured one at a time, with one input transition per measurement.
 - D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

APPLICATION INFORMATION

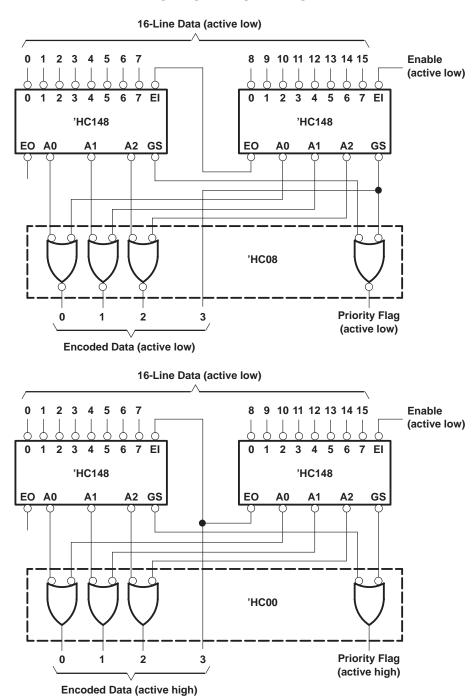


Figure 2. Priority Encoder for 16 Bits

Because the 'HC148 devices are combinational logic circuits, wrong addresses can appear during input transients. Moreover, a change from high to low at EI can cause a transient low on GS when all inputs are high. This must be considered when strobing the outputs.





PACKAGE OPTION ADDENDUM

6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN54HC148J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC148D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DW	OBSOLETE	SOIC	DW	16		TBD	Call TI	Call TI
SN74HC148DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148DWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC148NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC148NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC148NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC148FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC148J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54HC148W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

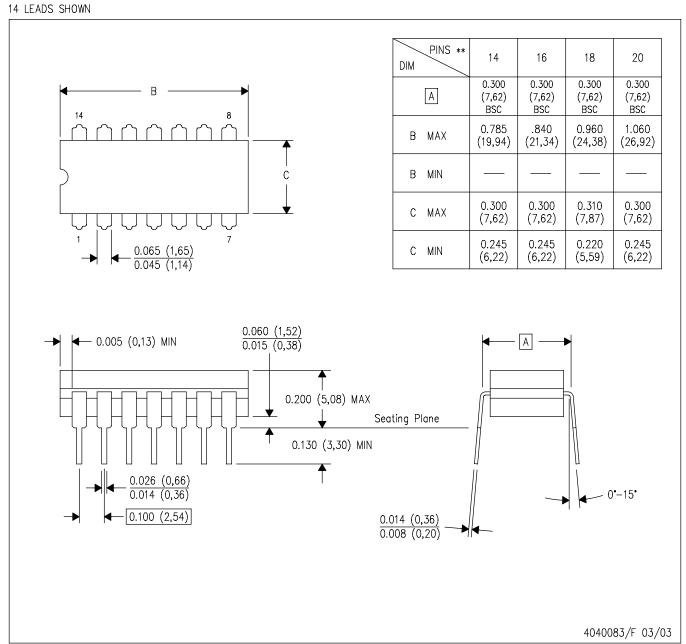


PACKAGE OPTION ADDENDUM

6-Dec-2006

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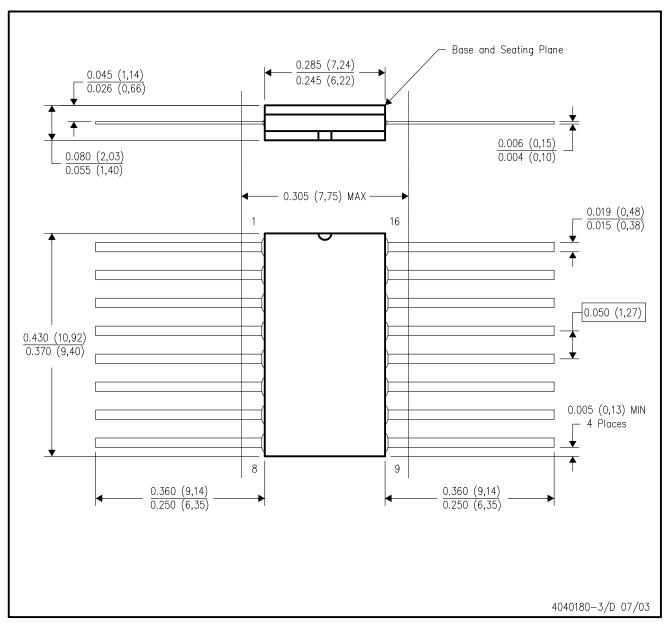
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- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



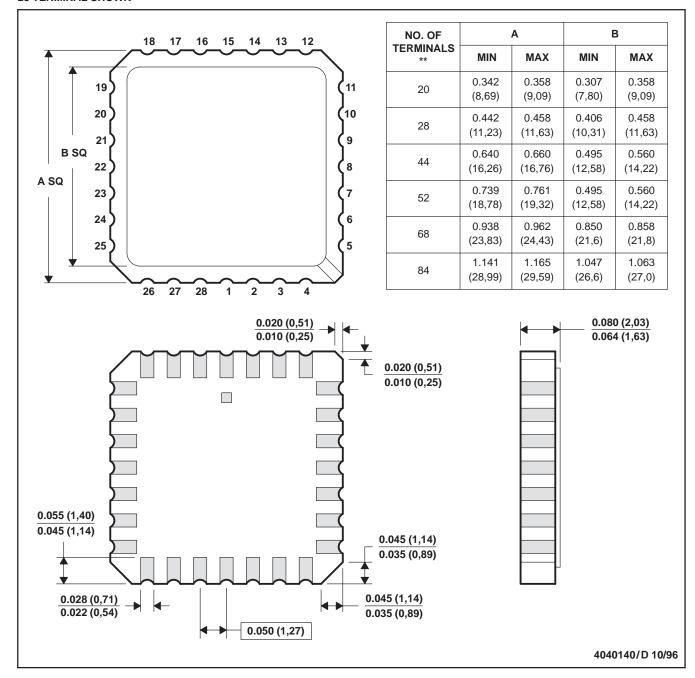
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- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



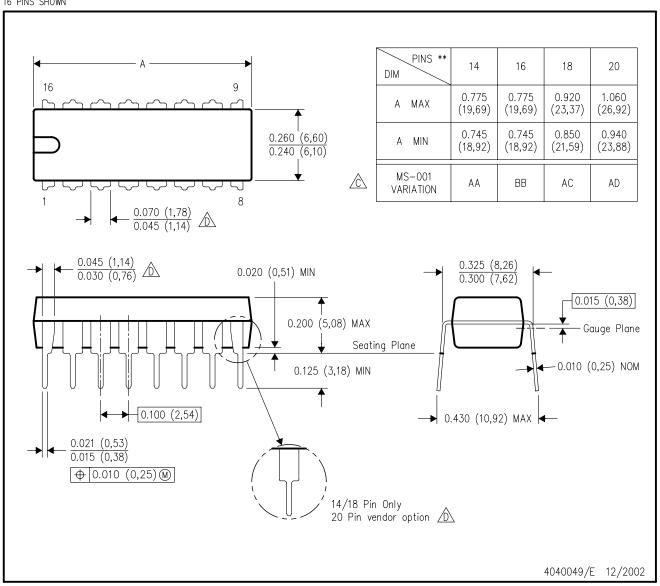
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

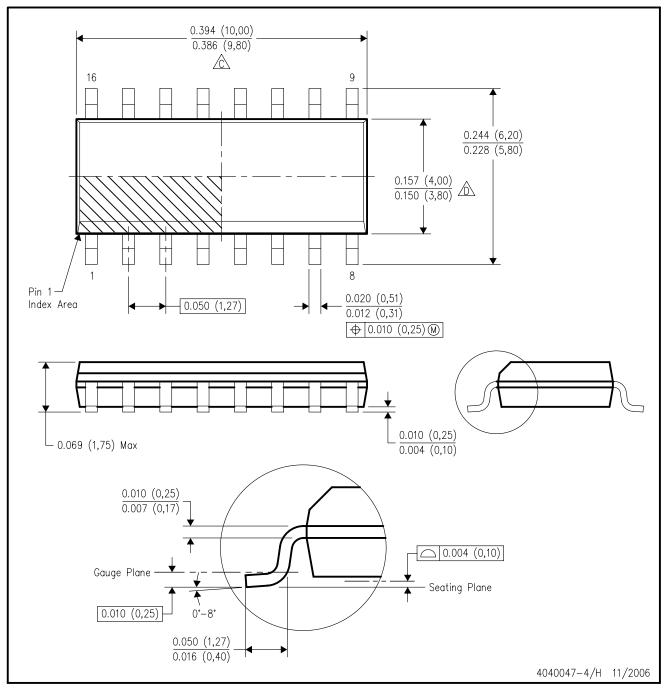


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE

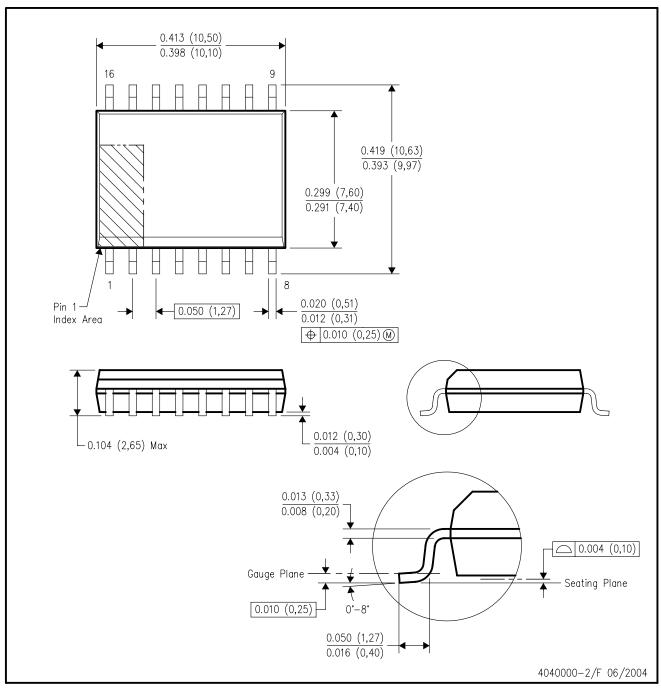


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.

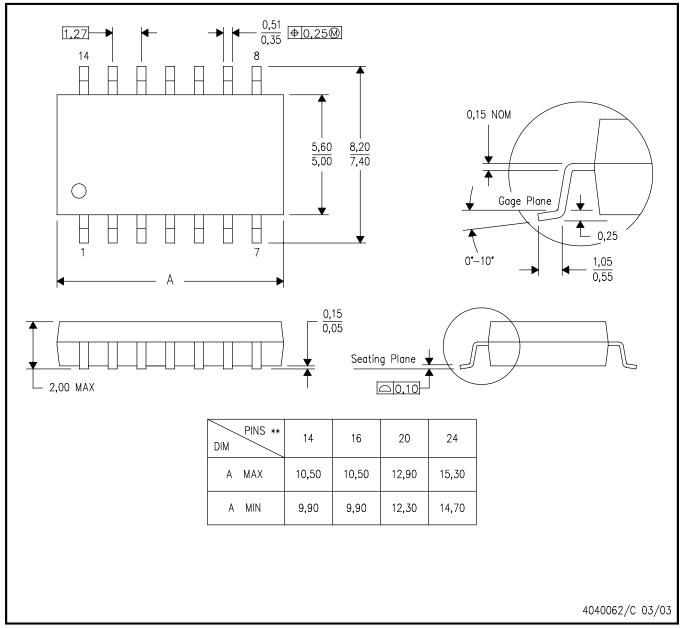


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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